



## 20V N-Channel Trench Power MOSFET

### General Description

The SJG8205 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

### Features

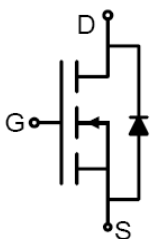
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### Application

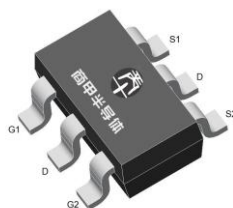
- 48V E-bike controller
- Uninterruptible power supply
- Hard switched and high frequency circuits

### Key Performance Parametes

| Parameter         | Value | Unit |
|-------------------|-------|------|
| $BV_{DSS\_TYP}$   | 16    | V    |
| $R_{DS(ON)\_TYP}$ | 21.8  | mΩ   |
| $I_D$             | 5.4   | A    |
| $Q_G$             | 15    | nC   |



Schematic Diagram



SOT23-6L top view



### Package Marking and Ordering Information

| Device/Ordering Code | Marking | Package  | Packing | Reel Size | Tape width | Quantity |
|----------------------|---------|----------|---------|-----------|------------|----------|
| SJG8205              | SJG8205 | SOT23-6L | Tape    | \         | \          | 3000 Pcs |

Table 1. Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)

| Symbol           | Parameter                                            | Limit      | Unit             |
|------------------|------------------------------------------------------|------------|------------------|
| $V_{DS}$         | Drain-Source Voltage ( $V_{GS}=0V$ )                 | 12         | V                |
| $V_{GS}$         | Gate-Source Voltage ( $V_{DS}=0V$ )                  | $\pm 12$   | V                |
| $I_D$            | Drain Current-Continuous( $T_A=25^\circ\text{C}$ )   | 5.4        | A                |
|                  | Drain Current-Continuous( $T_A=100^\circ\text{C}$ )  | 3.4        | A                |
| $I_{DM}$ (pluse) | Drain Current-Continuous@ Current-Pulsed (Note 1)    | 21.6       | A                |
| $P_D$            | Maximum Power Dissipation( $T_A=25^\circ\text{C}$ )  | 1.1        | W                |
|                  | Maximum Power Dissipation( $T_A=100^\circ\text{C}$ ) | 0.4        | W                |
| $E_{AS}$         | Avalanche energy (Note 2)                            | 6          | mJ               |
| $T_J, T_{STG}$   | Operating Junction and Storage Temperature Range     | -55 To 150 | $^\circ\text{C}$ |

Table 2. Thermal Characteristic

| Symbol          | Parameter                               | Typ | Max | Unit               |
|-----------------|-----------------------------------------|-----|-----|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient |     | 114 | $^\circ\text{C/W}$ |



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**Table 3. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

| Symbol                             | Parameter                         | Conditions                                                                              | Min | Typ  | Max  | Unit |
|------------------------------------|-----------------------------------|-----------------------------------------------------------------------------------------|-----|------|------|------|
| On/Off States                      |                                   |                                                                                         |     |      |      |      |
| BV <sub>DSS</sub>                  | Drain-Source Breakdown Voltage    | V <sub>GS</sub> =0V I <sub>D</sub> =250μA                                               | 12  |      |      | V    |
| I <sub>DSS</sub>                   | Zero Gate Voltage Drain Current   | V <sub>DS</sub> =12V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃                           |     |      | 1    | μA   |
|                                    |                                   | V <sub>DS</sub> =12V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃                          |     |      | 100  | μA   |
| I <sub>GSS</sub>                   | Gate-Body Leakage Current         | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V                                              |     |      | ±100 | nA   |
| V <sub>GS(th)</sub>                | Gate Threshold Voltage            | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                | 0.4 |      | 1    | V    |
| g <sub>FS</sub>                    | Forward Transconductance          | V <sub>DS</sub> =5V, I <sub>D</sub> =1.5A                                               |     | 6.6  |      | S    |
| R <sub>DS(ON)</sub>                | Drain-Source On-State Resistance  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =1.5A T <sub>J</sub> =25℃                         |     | 21.8 | 27.3 | mΩ   |
| R <sub>DS(ON)</sub>                | Drain-Source On-State Resistance  | V <sub>GS</sub> =2.5V, I <sub>D</sub> =1.5A T <sub>J</sub> =25℃                         |     | 30   | 39.9 | mΩ   |
| Dynamic Characteristics            |                                   |                                                                                         |     |      |      |      |
| C <sub>iss</sub>                   | Input Capacitance                 | V <sub>DS</sub> =6V,V <sub>GS</sub> =0V,<br>f=1.0MHz                                    |     | 784  |      | pF   |
| C <sub>oss</sub>                   | Output Capacitance                |                                                                                         |     | 74   |      | pF   |
| C <sub>rss</sub>                   | Reverse Transfer Capacitance      |                                                                                         |     | 65   |      | pF   |
| R <sub>g</sub>                     | Gate resistance                   | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz                                      |     | 16   |      | Ω    |
| Switching Parameters               |                                   |                                                                                         |     |      |      |      |
| t <sub>d(on)</sub>                 | Turn-on Delay Time                | V <sub>GS</sub> =4.5V, V <sub>DS</sub> =6V,<br>R <sub>L</sub> =4Ω, R <sub>GEN</sub> =3Ω |     | 6.4  |      | nS   |
| t <sub>r</sub>                     | Turn-on Rise Time                 |                                                                                         |     | 24   |      | nS   |
| t <sub>d(off)</sub>                | Turn-Off Delay Time               |                                                                                         |     | 23   |      | nS   |
| t <sub>f</sub>                     | Turn-Off Fall Time                |                                                                                         |     | 35   |      | nS   |
| Q <sub>g</sub>                     | Total Gate Charge                 | V <sub>GS</sub> =4.5V, V <sub>DS</sub> =6V, I <sub>D</sub> =1.5A                        |     | 15   |      | nC   |
| Q <sub>gs</sub>                    | Gate-Source Charge                |                                                                                         |     | 1.5  |      | nC   |
| Q <sub>gd</sub>                    | Gate-Drain Charge                 |                                                                                         |     | 1.7  |      | nC   |
| Source-Drain Diode Characteristics |                                   |                                                                                         |     |      |      |      |
| I <sub>SD</sub>                    | Source-Drain Current (Body Diode) |                                                                                         |     |      | 5.4  | A    |
| V <sub>SD</sub>                    | Forward on Voltage (Note 3)       | V <sub>GS</sub> =0V, I <sub>S</sub> =1.5A                                               |     |      | 1.2  | V    |
| t <sub>rr</sub>                    | Reverse Recovery Time             | I <sub>F</sub> =1.5A, dI/dt=100A/μs                                                     |     | 5.8  |      | ns   |
| Q <sub>rr</sub>                    | Reverse Recovery Charge           | I <sub>F</sub> =1.5A, dI/dt=100A/μs                                                     |     | 1.2  |      | nC   |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

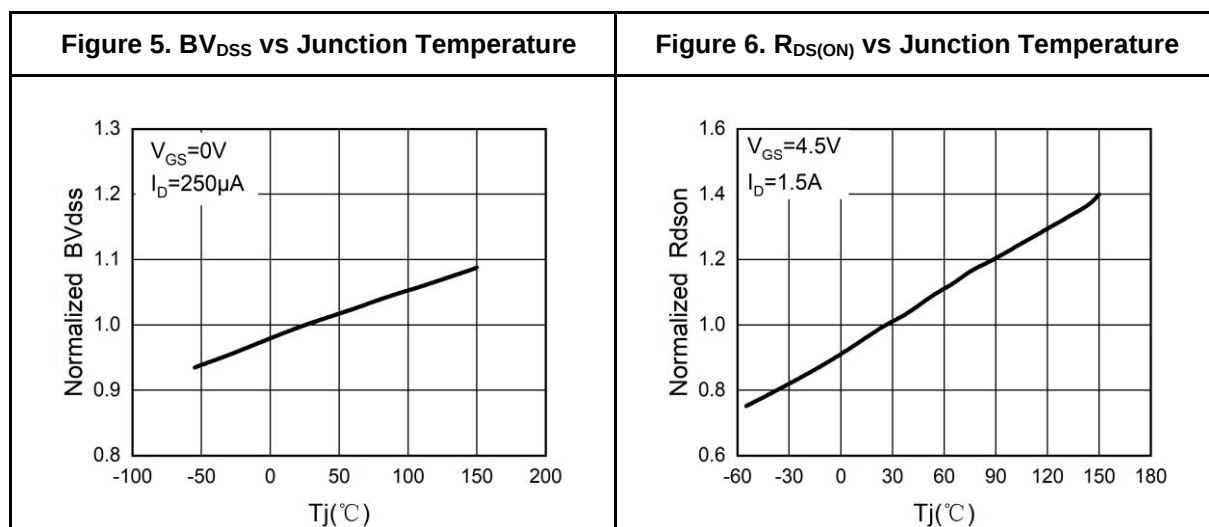
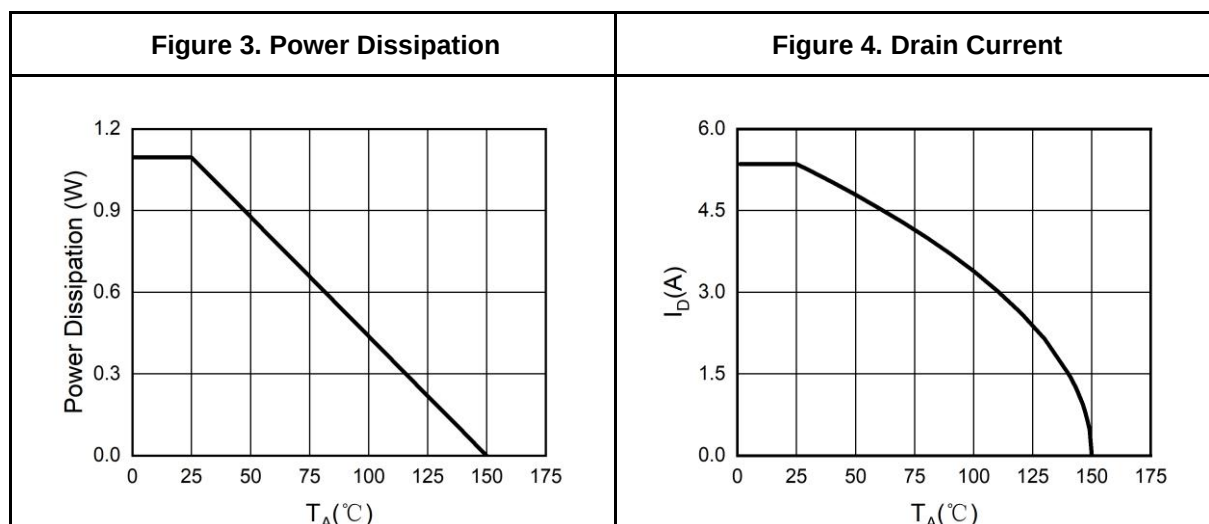
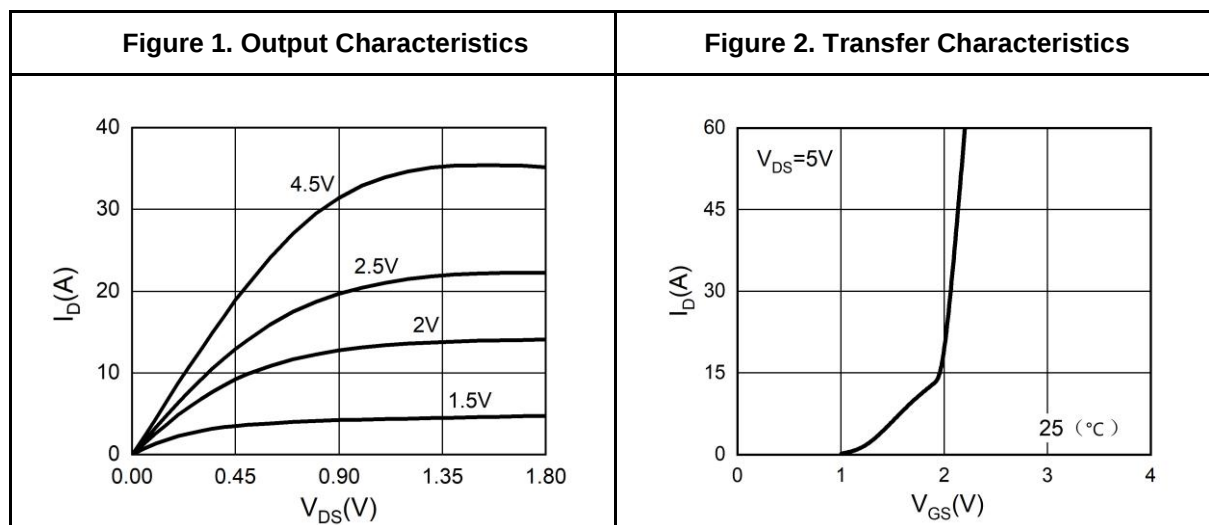
Notes 2.EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=12V, V_G=10V, R_g=25\Omega, L=0.5mH$ .

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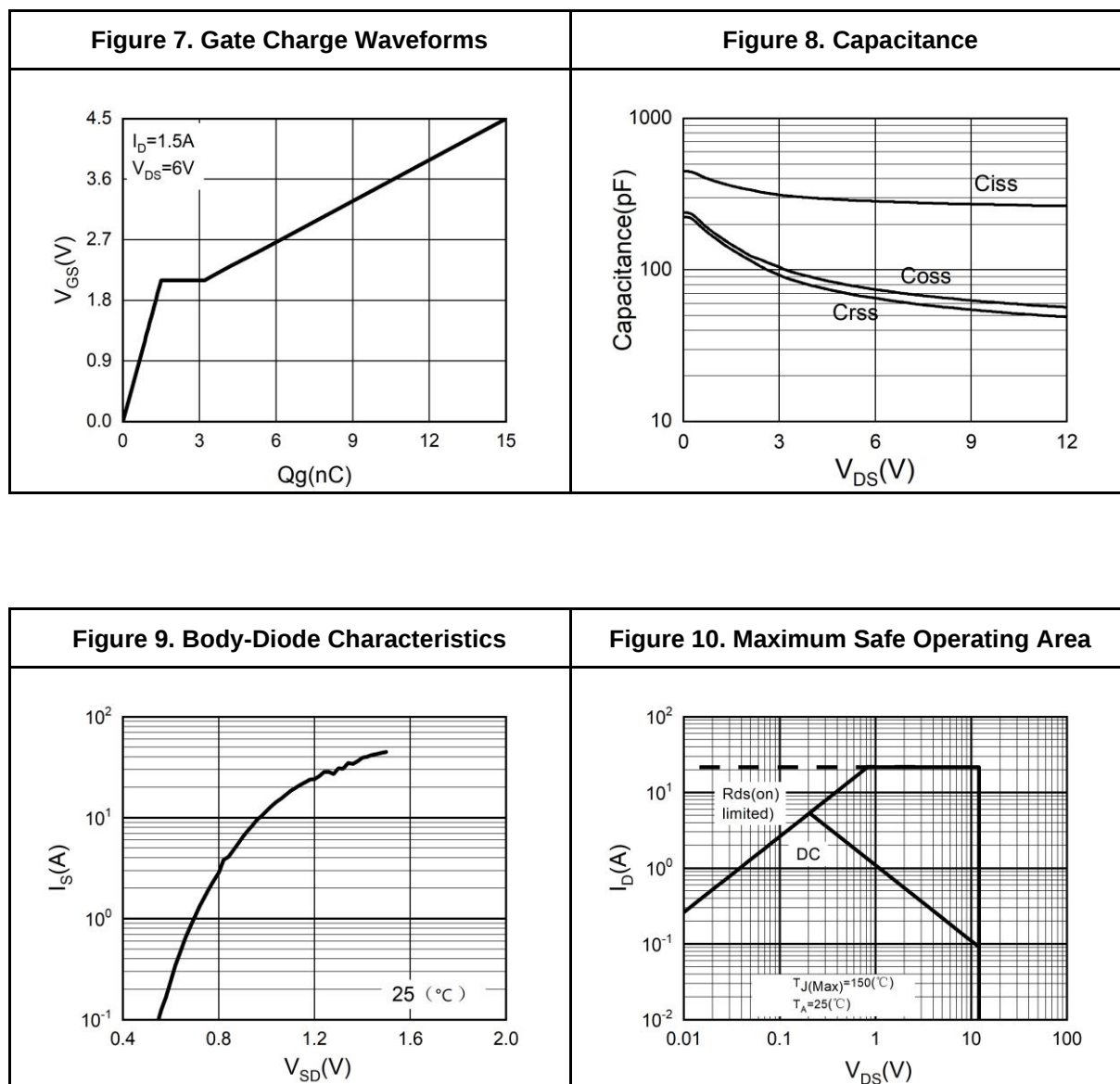
### Typical Electrical And Thermal Characteristics (Curves)





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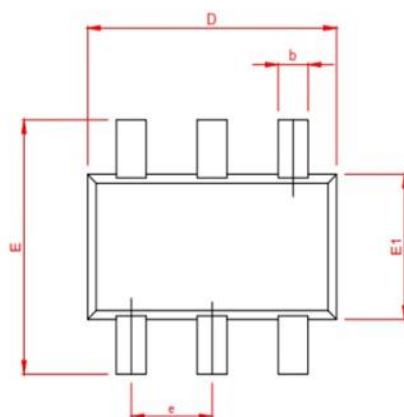
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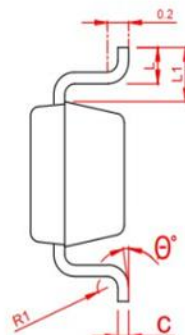


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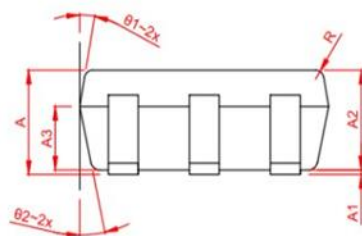
### SOT23-6L Package Information



TOP VIEW



SIDE VIEW



| SYMBOL  | MILLIMETER |      |      |
|---------|------------|------|------|
|         | MIN        | NOM  | MAX  |
| A       | 1.06       | 1.15 | 1.24 |
| * A1    | 0.01       | 0.05 | 0.09 |
| * A2    | 1.05       | 1.10 | 1.15 |
| A3      | 0.65       | 0.70 | 0.75 |
| * b     | 0.30       | 0.35 | 0.45 |
| * c     | 0.127REF   |      |      |
| * D     | 2.87       | 2.92 | 2.97 |
| * E     | 2.72       | 2.80 | 2.88 |
| * E1    | 1.55       | 1.60 | 1.65 |
| * e     | 0.95BSC    |      |      |
| * L     | 0.32       | 0.40 | 0.48 |
| * L1    | 0.55       | 0.60 | 0.65 |
| R       | 0.10 REF   |      |      |
| R1      | 0.12 REF   |      |      |
| * theta | 0          | --   | 8°   |
| theta1  | 8°         | 10°  | 12°  |
| theta2  | 10°        | 12°  | 14°  |



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